Am ndments to th Specification

Please replace paragraph starting at page 15, line 23:

The present embodiment of the signal probe head 30 is designed for circuit boards having a thickness of less than .090 inches. In this embodiment, the flanges 134 formed adjacent to the apertures 132 in the signal contact holder 60 are removed and replaced by alignment flanges 150 extending above the circuit board 32, 36. The alignment flanges 150 extend from a retention block 152 that is positioned on the opposite side of the circuit board 32, 26 from the contact pads 40. The retention block 152 has threaded apertures 154 formed therein that are aligned with the through holes 44 in the circuit board 32, 36. The alignment flanges 150 are formed adjacent to the threaded apertures 154 and are sized to be closely receives in the through holes 44 in the circuit board 32, 36. The flanges 150 extend above the surface of the circuit board 32, 36 and include latching members 156 that extend outward from the flanges 150 and engage the top surface of the circuit board 32, 36 to secure the retention block 152 to the circuit board. The signal probe head 30 is positioned on the circuit board 32, 26 36 with the flanges 150 extending into the second bores 89 in the housing 50 30 to help align the signal probe head 50 on the board. The latching members 156 of the retention block 152 are closely received in notches 158 formed adjacent to the open end 52 of the housing 50. The attachment members 90, in the form of the threaded screws positioned in the bores 88 of the housing 50, threadably mate with the threaded apertures 154 in the retention block 152. Tightening of the threaded screws 90 in the retention block 152 captures the circuit board 32, 36 between the retention block 152 and the signal probe head 30 and secures the signal probe head 30 to the circuit board 32,36.